L Nu	umber	Hits	Search Text		
2		59826	bond\$3 with (wints interest	DB	Time stamp
-		33020	bond\$3 with (wir\$3 interconnect\$3)	USPAT;	2004/05/14 12:38
4		38021	(bondes with this as	US-PGPUB	
-	•	30021	1 (2000) WEST (WILDS INCELCONNECTOR AND	USPAT;	2004/05/14 12:21
5		15665	(remov\$3 detach\$3)	US-PGPUB	
٦		15665	1 , ,	USPAT;	2004/05/14 12:22
1			(remov\$3 detach\$3)) and (light x?ray x-ray	US-PGPUB	12.22
-			("x" near3 "ray"))		1
6		8767	(((bond\$3 with (wir\$3 interconnect\$3)) and	USPAT;	2004/05/14 10 00
٠.			(remov\$3 detach\$3)) and (light v2ray v_ray	US-PGPUB	2004/05/14 12:22
		j	("x" near3 "ray"))) and ((second dummy	US-PGPUB	
			sacrificial temp\$8) near50 (base substrate		***
		1	wafer))	1	
7	,	6766	1		
			(removes detaches)) and	USPAT;	2004/05/14 12:19
l			(remov\$3 detach\$3)) and (light x?ray x-ray	US-PGPUB	
+			("x" near3 "ray"))) and ((second dummy		1
	•		sacrificial temp\$8) near50 (base substrate		
8		E0E00	wafer))) and (insulat\$3 dielectric)		0.10
٠.,		50503		USPAT;	2004/05/14 12:38
9	i	10000	(remov\$3 detach\$3 separat\$5)	US-PGPUB	22,30
9		19768	((bond\$3 with (wir\$3 interconnect\$3)) and	USPAT;	2004/05/14 12:38
			(remov\$3 detach\$3 separat\$5)) and (light	US-PGPUB	2001/05/14 12:38
- a ·		*	X?ray x-ray ("x" near3 "ray"))	10105	
10		10522	(((bond\$3 with (wir\$3 interconnect\$3)) and	USPAT;	2004/05/24 25 05
	٠. ا		(remov\$3 detach\$3 separat\$5)) and (light	US-PGPUB	2004/05/14 12:23
		* .	X?ray x-ray ("x" near3 "ray"))) and (/second	US-FGFUB	
	٠.	•	dummy sacrificial temp\$8) near50 (base		33
٠, ,,			substrate wafer))	• •	14.
11	1	- 1811	((((bond\$3 with (wir\$3 interconnect\$3)) and		*
		,	(remov\$3 detach\$3 separat\$5)) and (light	USPAT;	2004/05/14 12:39
•			x?ray x-ray ("x" near3 "ray"))) and ((second	US-PGPUB	
•		•	dummy sacrificial temp\$8) near50 (base	,	
		٠	substrate wafer))) and ((heat\$3 irrad\$6)		*
			same (removed detected the state of the same (nearly)		
			same (remov\$3 detach\$3 separat\$5) same	*	
			(second dummy sacrificial temp\$8) same (base substrate wafer))	9	
12	. [53946	hondes with (-
*	, [27240	bond\$3 with (wir\$3 interconnect\$3)	EPO; JPO;	2004/05/14 12:38
	- 1	_		DERWENT;	,, ==, == 22,30
13	- 1	6504	(h34h)	IBM TDB	
		6594	(bond\$3 with (wir\$3 interconnect\$3)) and	EPO; JPO;	2004/05/14 12:38
		· ·	(remov\$3 detach\$3 separat\$5)	DERWENT:	
14			<i>y</i>	IBM TDB	,***
T.A		434	((bond\$3 with (wir\$3 interconnect\$3)) and	EPO; JPO;	2004/05/14 10 00
			(remov\$3 detach\$3 separat\$5)) and (light	DERWENT;	2004/05/14 12:39
4 E		19	X?ray x-ray ("x" near3 "ray"))	IBM TDB	*
15		13	(((bond\$3 with (wir\$3 interconnect\$2)) and	EPO; JPO;	2004/05/11
		*	(remov\$3 detach\$3 separat\$5)) and (light	DEDMENT	2004/05/14 12:39
		*	X:ray X-ray ("X" near3 "ray"))) and (/hontes)	DERWENT;	
;	•		TITADO Same (removed detached constitution)	IBM_TDB	1
٠.			same (second dummy sacrificial temp\$8) same		·
	18	.	(base substrate wafer))	1	1
					·